

Silicon Switching Diode

- For high-speed switching applications
- Pb-free (RoHS compliant) package ¹⁾
- Qualified according AEC Q101


BAS16
BAS16W
BAS16-02L
BAS16-02V
BAS16-02W
BAS16-03W
BAS16S
BAS16U
BAS16-07L4


Type	Package	Configuration	Marking
BAS16	SOT23	single	A6s
BAS16-02L*	TSLP-2-1	single, leadless	A6
BAS16-02V	SC79	single	6
BAS16-02W	SCD80	single	A6
BAS16-03W	SOD323	single	white B
BAS16-07L4*	TSLP-4-4	parallel pair, leadless	6A
BAS16S	SOT363	parallel triple	A6s
BAS16U	SC74	parallel triple	A6s
BAS16W	SOT323	single	A6s

* Preliminary Data

¹Pb-containing package may be available upon special request

Maximum Ratings at $T_A = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	80	V
Peak reverse voltage	V_{RM}	85	
Forward current	I_F		mA
BAS16		250	
BAS16-02L, -07L4		200	
BAS16-02V, -02W		200	
BAS16-03W		250	
BAS16S		200	
BAS16U		200	
BAS16W		250	
Non-repetitive peak surge forward current	I_{FSM}		A
$t = 1\ \mu\text{s}$, BAS16/ S/ U/ W/ -03W		4.5	
$t = 1\ \mu\text{s}$, BAS16-02L/ -02V/ -02W/ -07L4		2.5	
$t = 1\ \text{s}$		0.5	
Total power dissipation	P_{tot}		mW
BAS16, $T_S \leq 54\text{ °C}$		370	
BAS16-02L, -07L4, $T_S \leq 130\text{ °C}$		250	
BAS16-02V, -02W, $T_S \leq 120\text{ °C}$		250	
BAS16-03W, $T_S \leq 116\text{ °C}$		250	
BAS16S, $T_S \leq 85\text{ °C}$		250	
BAS16U, $T_S \leq 113\text{ °C}$		250	
BAS16W, $T_S \leq 119\text{ °C}$		250	
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}		K/W
BAS16, BAS16S		≤ 260	
BAS16-02L, -07L4		≤ 80	
BAS16-02V, -02W		≤ 120	
BAS16-03W		≤ 135	
BAS16U		≤ 150	
BAS16W		≤ 125	

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Breakdown voltage $I_{(BR)} = 100 \mu\text{A}$	$V_{(BR)}$	85	-	-	V
Reverse current $V_R = 75 \text{ V}$ $V_R = 25 \text{ V}, T_A = 150^\circ\text{C}$ $V_R = 75 \text{ V}, T_A = 150^\circ\text{C}$	I_R	-	-	1 30 50	μA
Forward voltage $I_F = 1 \text{ mA}$ $I_F = 10 \text{ mA}$ $I_F = 50 \text{ mA}$ $I_F = 100 \text{ mA}$ $I_F = 150 \text{ mA}$	V_F	-	-	715 855 1000 1200 1250	mV
Forward recovery voltage $I_F = 10 \text{ mA}, t_P = 20 \text{ ns}$	V_{fr}	-	-	1.75	V

¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics					
Diode capacitance $V_R = 0\text{ V}, f = 1\text{ MHz}$	C_T	-	-	2	pF
Reverse recovery time $I_F = 10\text{ mA}, I_R = 10\text{ mA}$, measured at $I_R = 1\text{ mA}$, $R_L = 100\ \Omega$	t_{rr}	-	-	4	ns

Test circuit for reverse recovery time


Pulse generator: $t_p = 100\text{ ns}$, $D = 0.05$, $t_r = 0.6\text{ ns}$,
 $R_i = 50\ \Omega$

Oscilloscope: $R = 50\ \Omega$, $t_r = 0.35\text{ ns}$, $C = 0.05\text{ pF}$

Reverse current $I_R = f(T_A)$

$V_R =$ Parameter



Forward Voltage $V_F = f(T_A)$

$I_F =$ Parameter



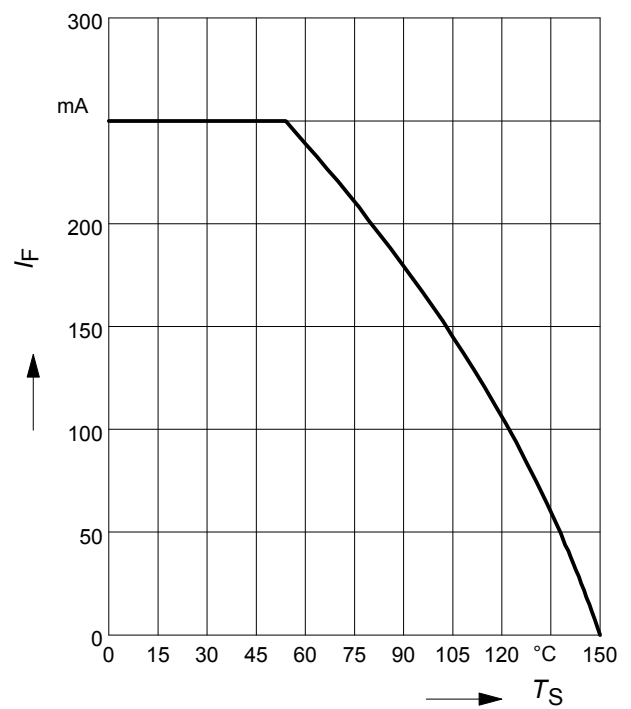
Forward current $I_F = f(V_F)$

$T_A = 25^\circ\text{C}$



Forward current $I_F = f(T_S)$

BAS16



Forward current $I_F = f(T_S)$

BAS16-02L, -07L4



Forward current $I_F = f(T_S)$

BAS16-02V, -02W



Forward current $I_F = f(T_S)$

BAS16-03W



Forward current $I_F = f(T_S)$

BAS16S



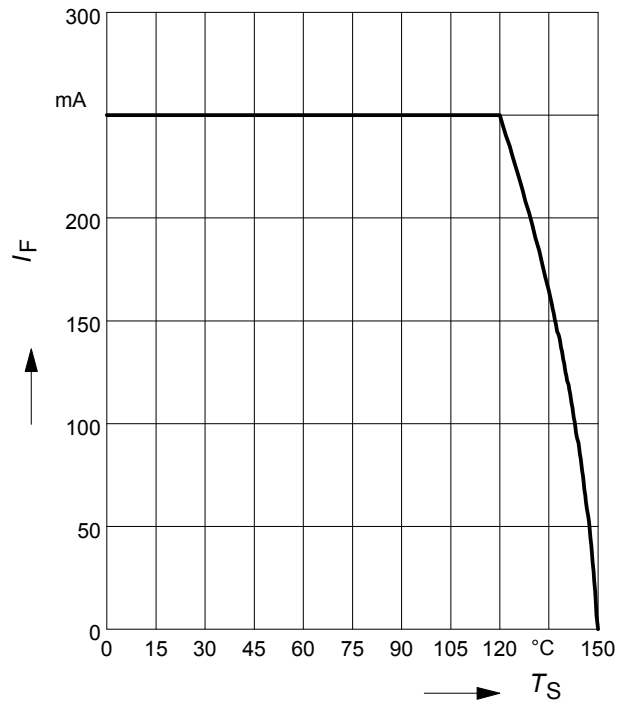
Forward current $I_F = f(T_S)$

BAS16U



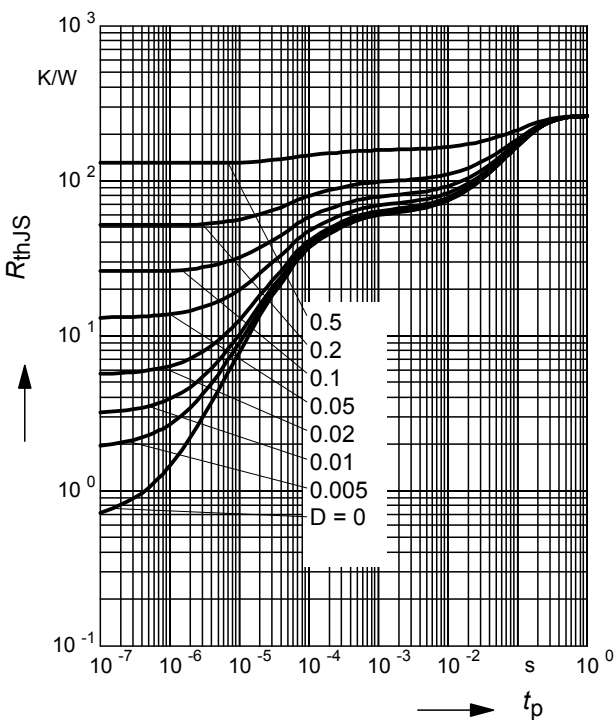
Forward current $I_F = f(T_S)$

BAS16W



Permissible Puls Load $R_{thJS} = f(t_p)$

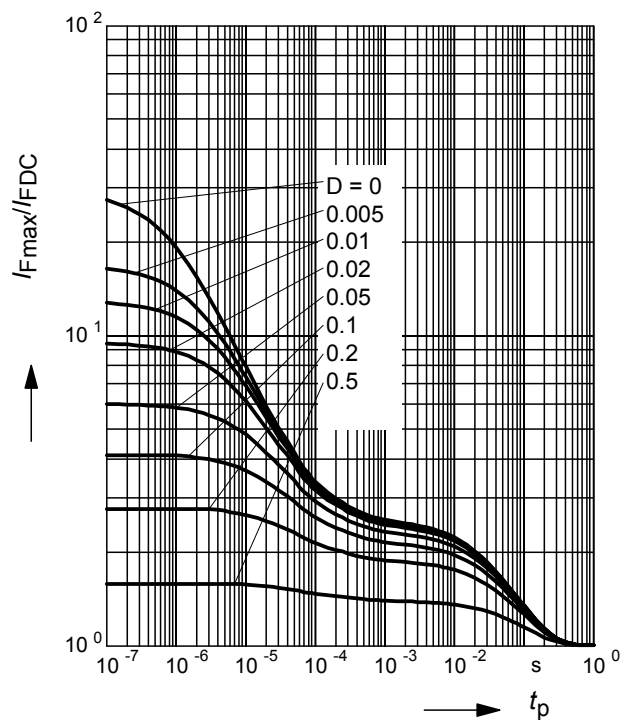
BAS16



Permissible Pulse Load

$I_{Fmax} / I_{FDC} = f(t_p)$

BAS16



Permissible Puls Load $R_{thJS} = f(t_p)$

BAS16-02L, -07L4



Permissible Pulse Load

$I_{Fmax} / I_{FDC} = f(t_p)$

BAS16-02L, -07L4



Permissible Puls Load $R_{thJS} = f(t_p)$

BAS16-02V, -02W



Permissible Pulse Load

$I_{Fmax} / I_{FDC} = f(t_p)$

BAS16-02V, -02W



Permissible Puls Load $R_{thJS} = f(t_p)$

BAS16-03W



Permissible Pulse Load

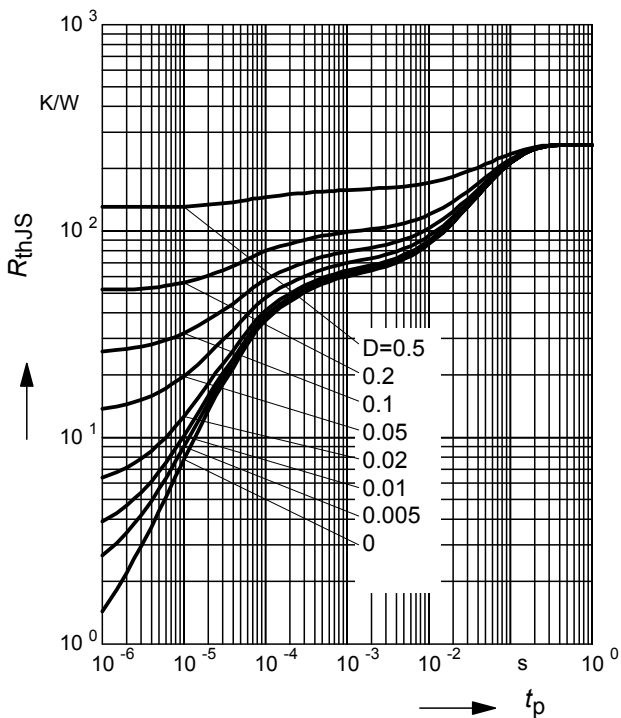
$I_{Fmax} / I_{FDC} = f(t_p)$

BAS16-03W



Permissible Puls Load $R_{thJS} = f(t_p)$

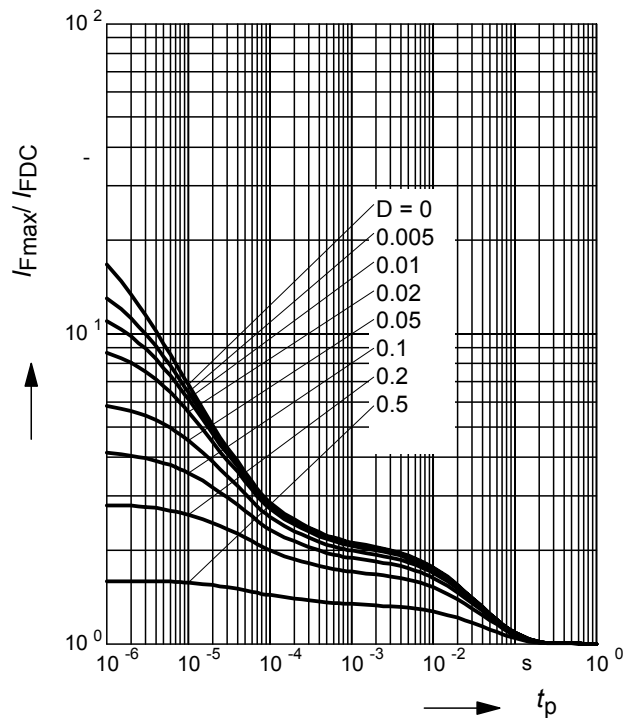
BAS16S



Permissible Pulse Load

$I_{Fmax} / I_{FDC} = f(t_p)$

BAS16S



Permissible Puls Load $R_{thJS} = f(t_p)$

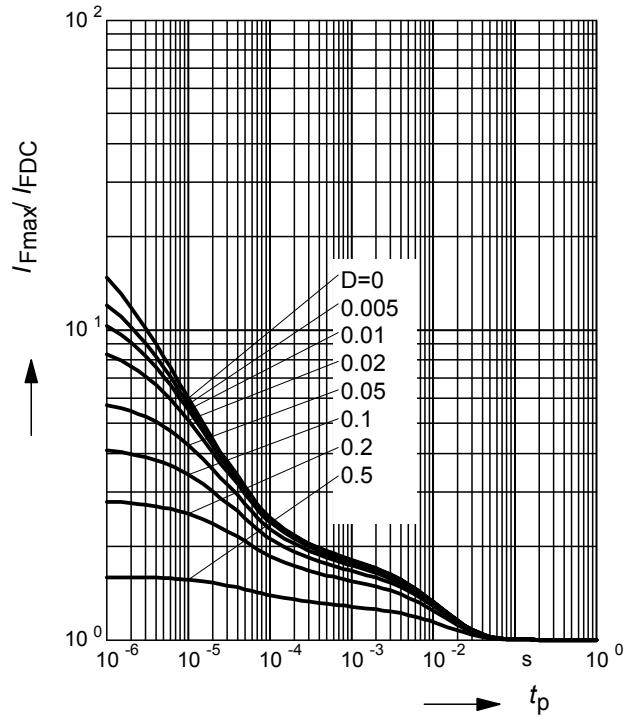
BAS16U



Permissible Pulse Load

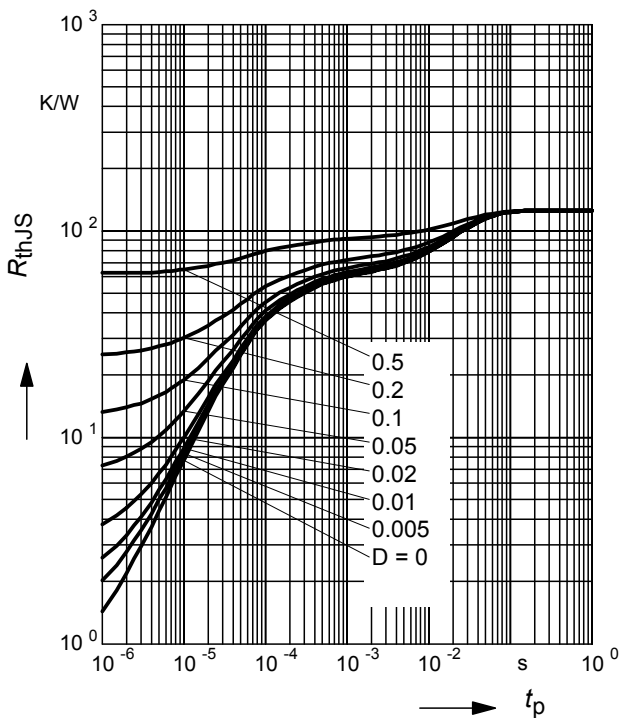
$I_{Fmax} / I_{FDC} = f(t_p)$

BAS16U



Permissible Puls Load $R_{thJS} = f(t_p)$

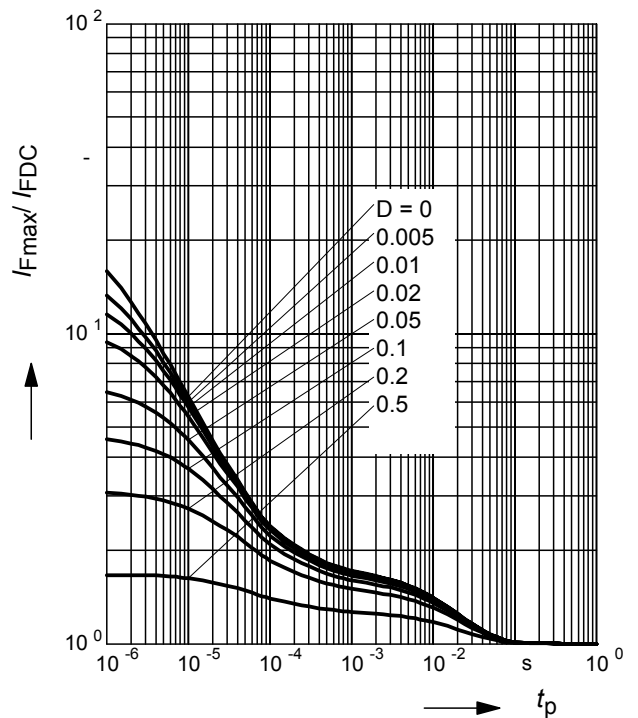
BAS16W



Permissible Pulse Load

$I_{Fmax} / I_{FDC} = f(t_p)$

BAS16W



Package Outline



Foot Print



Marking Layout (Example)

Small variations in positioning of Date code, Type code and Manufacture are possible.



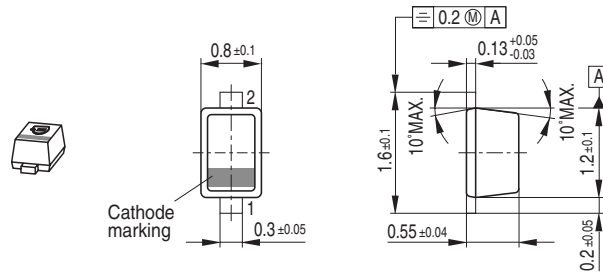
Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel

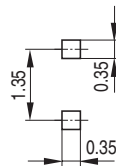
For symmetric types no defined Pin 1 orientation in reel.



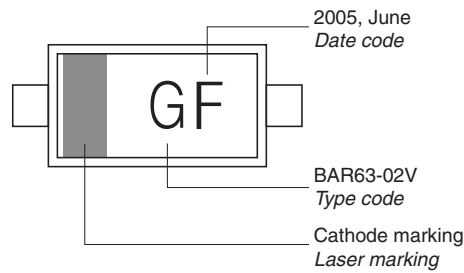
Package Outline



Foot Print



Marking Layout (Example)



Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 180 mm = 8.000 Pieces/Reel (2 mm Pitch)
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



Package Outline



Foot Print



Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)
 Reel ø330 mm = 10.000 Pieces/Reel

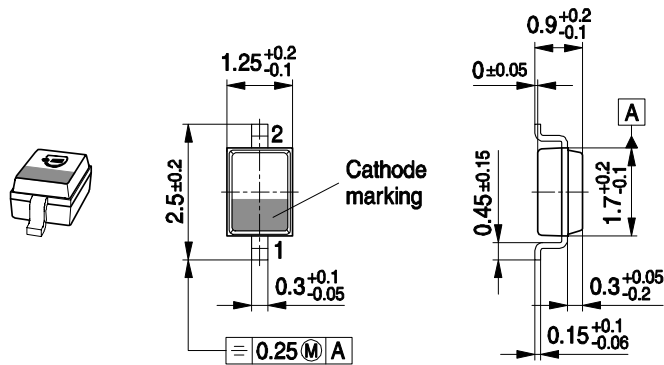


Date Code marking for discrete packages with one digit (SCD80, SC79, SC75¹⁾) CES-Code

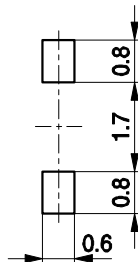
Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

1) New Marking Layout for SC75, implemented at October 2005.

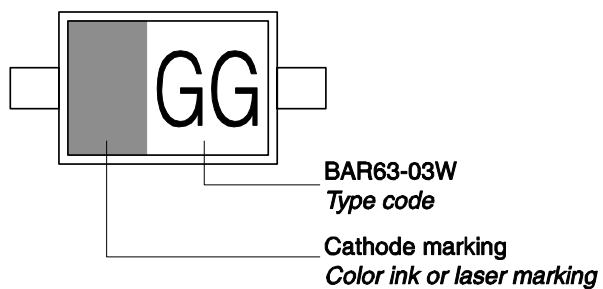
Package Outline



Foot Print

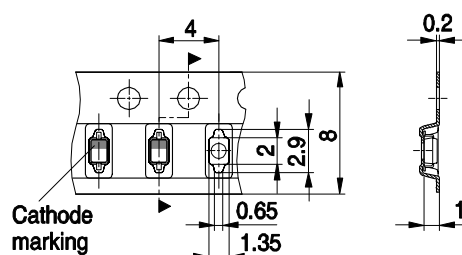


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø330 mm = 10.000 Pieces/Reel



Package Outline



1) Lead width can be 0.6 max. in dambar area

Foot Print



Marking Layout (Example)



Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



Package Outline



Foot Print



Marking Layout (Example)



Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



Package Outline

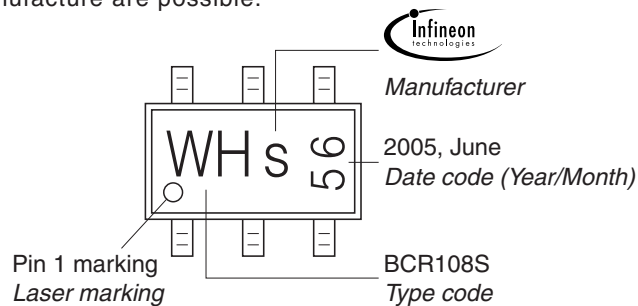


Foot Print



Marking Layout (Example)

Small variations in positioning of Date code, Type code and Manufacturer are possible.



Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.



Package Outline



1) Dimension applies to plated terminal

Foot Print

For board assembly information please refer to Infineon website "Packages"



■ Copper □ Solder mask

▨ Stencil apertures

Marking Layout (Example)



BAS16-02L
Type code

Cathode marking
Laser marking

Standard Packing

Reel \varnothing 180 mm = 15.000 Pieces/Reel
Reel \varnothing 330 mm = 50.000 Pieces/Reel (optional)



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